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April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

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#### MOS FIELD EFFECT TRANSISTOR

2SK3431

## SWITCHING N-CHANNEL POWER MOS FET

#### **DESCRIPTION**

The 2SK3431 is N-channel MOS Field Effect Transistor designed for high current switching applications.

#### **FEATURES**

• Super low on-state resistance:

 $R_{DS(on)1} = 5.6 \, m\Omega \, MAX. \, (V_{GS} = 10 \, V, \, I_{D} = 42 \, A)$   $R_{DS(on)2} = 8.9 \, m\Omega \, MAX. \, (V_{GS} = 4 \, V, \, I_{D} = 42 \, A)$ 

- Low Ciss: Ciss = 6100 pF TYP.
- Built-in gate protection diode

#### ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3431	TO-220AB
2SK3431-S	TO-262
2SK3431-ZJ	TO-263
2SK3431-Z	TO-220SMD <sup>Note</sup>

**Note** TO-220SMD package is produced only in Japan.

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	40	V
Gate to Source Voltage (Vps = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±83	Α
Drain Current (pulse) Note1	D(pulse)	±332	Α
Total Power Dissipation (Tc = 25°C)	Рт	100	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	Рт	1.5	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note2	las	65	Α
Single Avalanche Energy Note2	Eas	423	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty cycle  $\leq$  1%

**2.** Starting T<sub>ch</sub> = 25°C, V<sub>DD</sub> = 20 V, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = 20  $\rightarrow$  0 V

(TO-220AB)



(TO-262)



(TO-263, TO-220SMD)



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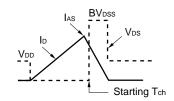


#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

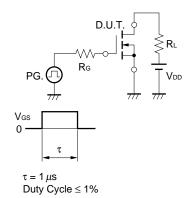
	<u> </u>	1				
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Ipss	Vps = 40 V, Vgs = 0 V			10	μΑ
Gate Leakage Current	Igss	Vgs = ±20 V, Vps = 0 V			±10	μΑ
Gate Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	2.0	2.5	V
Forward Transfer Admittance	y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 42 A	30	60		S
Drain to Source On-state Resistance	RDS(on)1	Vgs = 10 V, ID = 42 A		4.5	5.6	mΩ
	RDS(on)2	Vgs = 4 V, ID = 42 A		6.2	8.9	mΩ
Input Capacitance	Ciss	Vps = 10 V		6100		pF
Output Capacitance	Coss	Vgs = 0 V		1400		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		700		pF
Turn-on Delay Time	<b>t</b> d(on)	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 42 A		120		ns
Rise Time	<b>t</b> r	V <sub>G</sub> S = 10 V		1800		ns
Turn-off Delay Time	td(off)	$R_G = 10 \Omega$		350		ns
Fall Time	<b>t</b> f			440		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 32 V		110		nC
Gate to Source Charge	Qgs	V <sub>GS</sub> = 10 V		18		nC
Gate to Drain Charge	Q <sub>GD</sub>	ID = 83 A		31		nC
Body Diode Forward Voltage	V <sub>F(S-D)</sub>	IF = 83 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 83 A, VGS = 0 V		65		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		110		nC

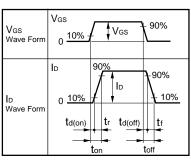
#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $\begin{array}{c} \text{D.U.T.} \\ \text{RG} = 25 \ \Omega \\ \text{PG.} \\ \\ \text{V}_{\text{GS}} = 20 \rightarrow 0 \ \text{V} \\ \end{array} \begin{array}{c} \text{S} \\ \text{50} \ \Omega \\ \\ \text{W} \end{array} \begin{array}{c} \text{V}_{\text{DD}} \\ \\ \text{W} \end{array}$



#### TEST CIRCUIT 2 SWITCHING TIME



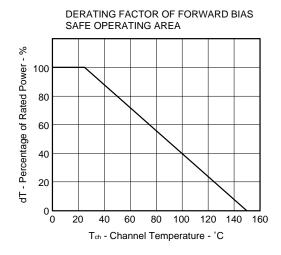


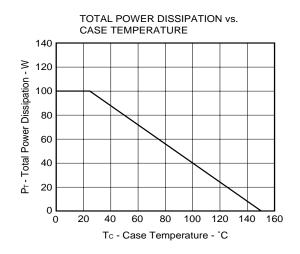
#### **TEST CIRCUIT 3 GATE CHARGE**

PG. 
$$\bigcirc$$
 So  $\Omega$   $\bigcirc$  RL

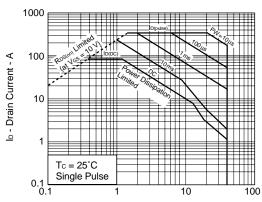


#### TYPICAL CHARACTERISTICS (TA = 25°C)



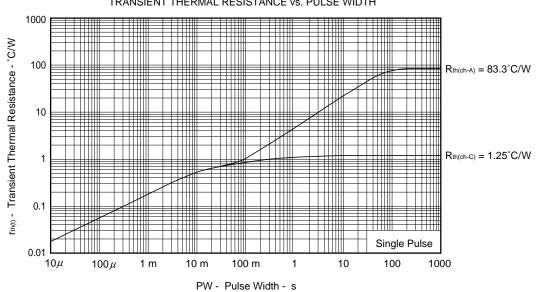


#### FORWARD BIAS SAFE OPERATING AREA

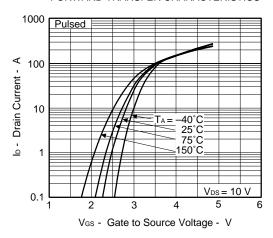


Vps - Drain to Source Voltage - V

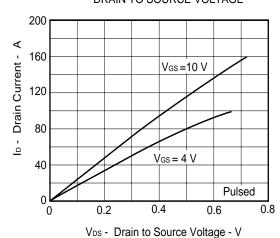
#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



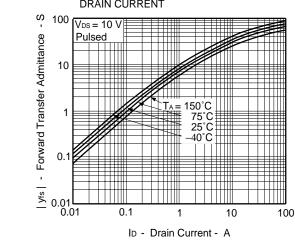
#### FORWARD TRANSFER CHARACTERISTICS



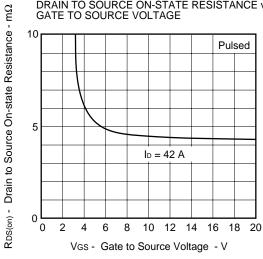
## DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



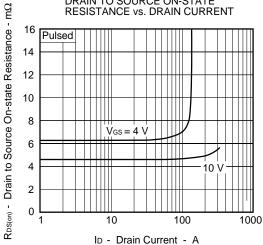
#### FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



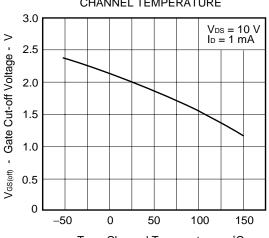
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



## DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

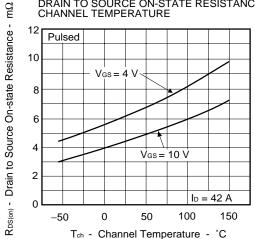


GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE

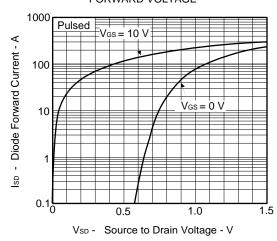




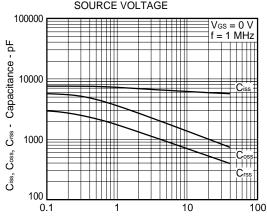
## DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



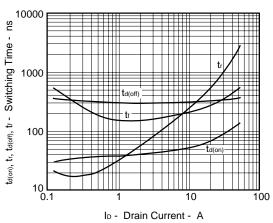
## SOURCE TO DRAIN DIODE FORWARD VOLTAGE



## CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

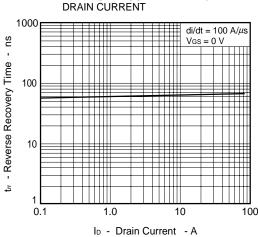


SWITCHING CHARACTERISTICS

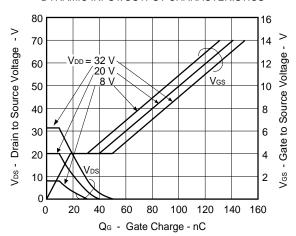


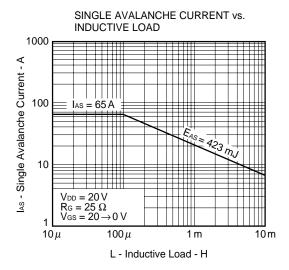
#### REVERSE RECOVERY TIME vs.

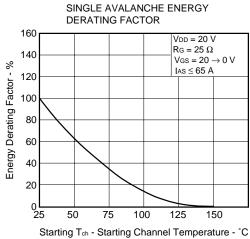
V<sub>DS</sub> - Drain to Source Voltage - V



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



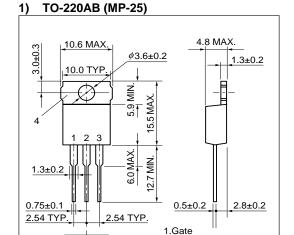






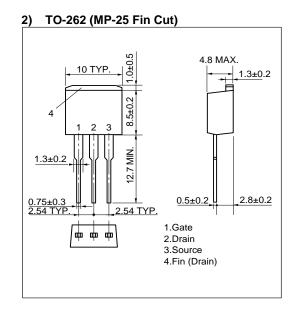
#### **★ PACKAGE DRAWINGS (Unit: mm)**

**# #** 

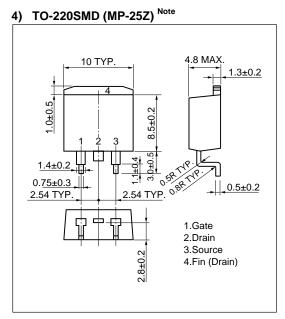


2.Drain

3.Source 4.Fin (Drain)

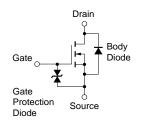


#### 3) TO-263 (MP-25ZJ) 10 TYP. 1.3±0.2 .0±0.5 $8.5\pm0.2$ 1.4±0.2 0.8R TYP. $0.7 \pm 0.2$ 0.5±0.2 2.54 TYP. 2.54 TYP. 1.Gate 2.Drain 3.Source $2.8 \pm 0.2$ 4.Fin (Drain)



Note This package is produced only in Japan.

#### **EQUIVALENT CIRCUIT**



Remark

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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